

**Final Product Change Notification**

202008003F01

**Issue Date:** 01-Oct-2020  
**Effective Date:** 30-Mar-2021

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia.  
 For detailed information we invite you to view this notification online



**Management Summary**

- Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)
- For automotive products

**Change Category**

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input checked="" type="checkbox"/> Design              |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Improved leadless 5/6 pad packages incl die optimization to achieve zero delamination

**Details of this Change**

Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia) for automotive products

- Where necessary optimized die for legacy leadless packages
- Improved die aspect ratio and bond-pad relocation to improve intrinsic quality for wire-bond process and support zero delamination
- Identical IP used resulting in same performance as existing die
- BOM change for zero delamination performance
- Enhanced mould compound
- Introduced rough PPF inner leadframe
- Changed lead finish from Sn to enhanced NiPdAu (alignment with packages which were released since 2015)

- No change in diffusion fab and assembly location

Qualification in accordance to the Automotive Electronics Council:

- AEC-Q100-rev. H Stress Test Qualification for Integrated Circuits
- AEC-Q006-rev. A Qualification requirements for Cu wire interconnection

### Why do we Implement this Change

To improve the intrinsic quality

### Identification of Affected Products

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

## Product Availability

### Sample Information

Samples are available upon request

Samples are available upon request via Helpdesk+ from BG Analog & Logic ICs sample store in Nijmegen The Netherlands

### Production

Planned first shipment 30-Mar-2021

## Impact

SOT886/1202/1115: No change

SOT1226/1255: No change in fit, function, quality or reliability anticipated. Pads have rounded edges to enhance adhesion/locking. No change on recommended solder footprint

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Related Notifications

Notification	Issue Date	Effective Date	Title
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201912002F0131	Dec-2019	30-Mar-2020	Improved leadless 5/6 pad packages incl die optimization to achieve zero delamination
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## Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Oct-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## Remarks

- No change in data sheet electrical specification, test limits and distributions
- No assembly location change
- No fab location change
- Outline drawing products with SOT1226 and SOT1255 will show rounded edges on pads. (A new datasheet will be issued)

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**e-mail address** PCN-Logic@nexperia.com

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

## About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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Nexperia |

Nexperia B.V.

Jonkerbosplein 52 6534 AB Nijmegen, The Netherlands

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
74LVC1G08GM-Q100X	935690713115	74LVC1G08GM-Q100	Single 2-input AND gate	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC2G14GM-Q100X	935690714115	74LVC2G14GM-Q100	Dual inverting Schmitt trigger	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1G07GS-Q100H	935690778125	74LVC1G07GS-Q100	Buffer with open-drain o/p	SOT1202	X2SON6	RFS	Analog & Logic ICs
74LVC1G32GM-Q100H	935299288125	74LVC1G32GM-Q100	Single 2-input OR gate	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP1G125GM-Q100X	935690726115	74AUP1G125GM-Q100	Low power bufferline driver	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC2G04GS-Q100H	935690676125	74LVC2G04GS-Q100	Low Voltage Dual Inverter	SOT1202	X2SON6	RFS	Analog & Logic ICs
74AUP1G08GM-Q100X	935690769115	74AUP1G08GM-Q100	Low-power 2-input AND gate	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC2G34GM-Q100,1	935299049125	74LVC2G34GM-Q100	Dual buffer gate	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP1G125GS-Q100H	935690772125	74AUP1G125GS-Q100	2 supply translator/transceiver	SOT1202	X2SON6	RFS	Analog & Logic ICs
74AVC1T45GM-Q100H	935299489125	74AVC1T45GM-Q100	Dual supply xlator w/3-state	SOT886	XSON6	RFS	Analog & Logic ICs
74AVC1T45GS-Q100H	935690771125	74AVC1T45GS-Q100	2 supply translator/transceiver	SOT1202	X2SON6	RFS	Analog & Logic ICs
74LVC2GU04GM-Q100,	935299056125	74LVC2GU04GM-Q100	Dual inverter	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1G17GM-Q100X	935690764115	74LVC1G17GM-Q100	Single Schmitt trigger buffer	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1T45GM-Q100X	935690846115	74LVC1T45GM-Q100	1 bit dual supply transceiver	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1G125GM-Q100X	934660723115	74LVC1G125GM-Q100	Single bus buffer/line driver	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP1G157GM-Q100X	935690765115	74AUP1G157GM-Q100	Low-power 2-input mux	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP1G32GM-Q100X	935690767115	74AUP1G32GM-Q100	Low-power 2-input OR-gate	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP2GU04GM-Q100X	935690768115	74AUP2GU04GM-Q100	Low-power dual unbuffered inverter	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1G14GM-Q100X	935690763115	74LVC1G14GM-Q100	Single Schmitt-trigger inverter	SOT886	XSON6	RFS	Analog & Logic ICs
74LVC1G3157GM-Q10X	935300911115	74LVC1G3157GM-Q100	2-channel analog mux/dmux	SOT886	XSON6	RFS	Analog & Logic ICs
74AUP1T34GM-Q100X	935690766115	74AUP1T34GM-Q100	Low-power 2 supply buffer	SOT886	XSON6	RFS	Analog & Logic ICs